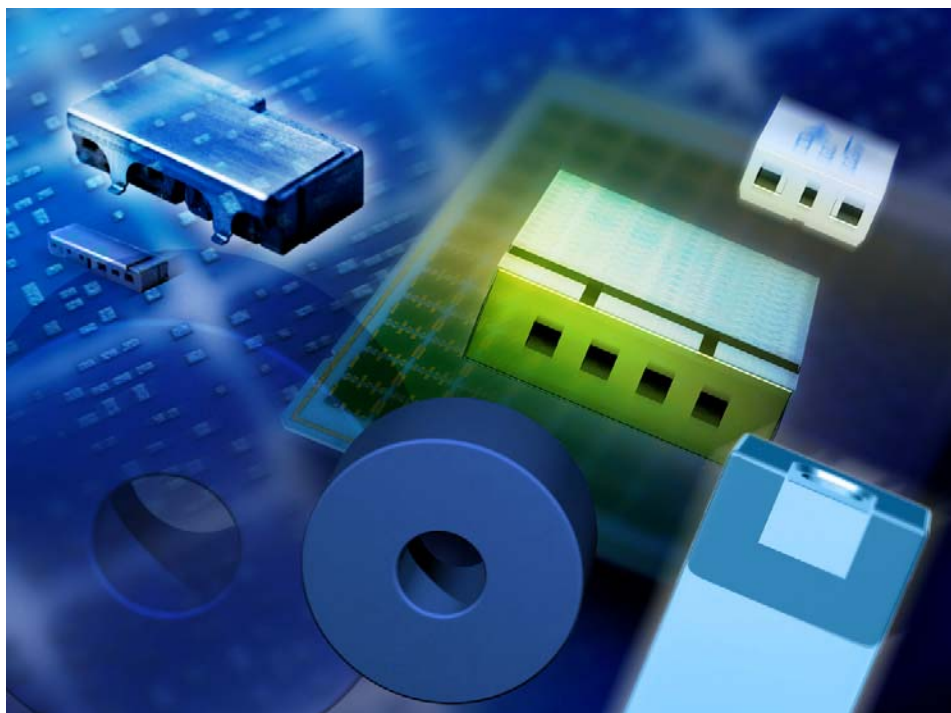




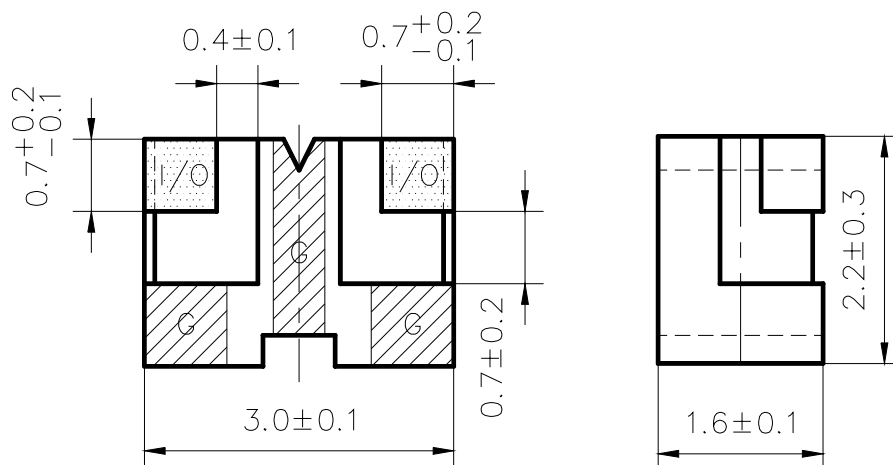
Features

- SMD filter consisting of coupled resonators with stepped impedances
- $\text{MgTiO}_3 - \text{CaTiO}_3$ ($\epsilon_r = 21$ / $TC_f = 0 \pm 10$ ppm/K) with a coating of copper ($10\mu\text{m}$) and tin ($>5\mu\text{m}$)
- Excellent reflow solderability, no migration effect due to copper/tin metallization

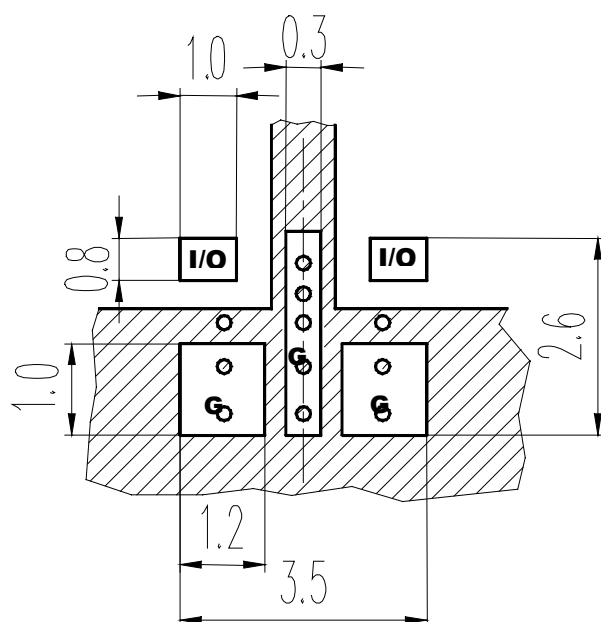
Index

- | | |
|--------|---|
| Page 2 | <ul style="list-style-type: none"> ● Component drawing ● Recommended footprint |
| Page 3 | <ul style="list-style-type: none"> ● Characteristics ● Maximum ratings ● Typical passband characteristic |
| Page 4 | <ul style="list-style-type: none"> ● Processing information ● Soldering requirements ● Delivery mode |

ISSUE DATE	19.03.04	ISSUE	P1	PUBLISHER	SAW MWC PD	PAGE	1/4
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Preliminary Data Sheet
Component drawing


View from below onto the solder terminals and view from beside

Recommended footprint


□ soldering area
via diameter 0.3mm

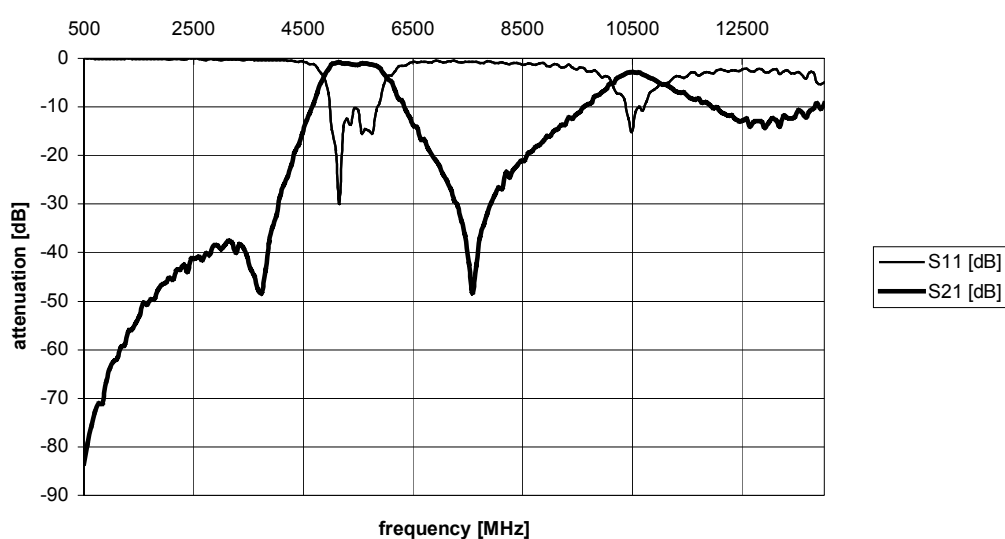
ISSUE DATE	19.03.04	ISSUE	P1	PUBLISHER	SAW MWC PD	PAGE	2/4
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Preliminary Data Sheet
Characteristics

		min.	typ.	max.	
Center frequency	f_C			5.5	GHz
Insertion loss [5150 – 5850] MHz	α_{IL}		1.4	1.5	dB
Passband [5150 – 5850] MHz	B	700			MHz
Amplitude ripple (peak - peak) [5150 – 5850] MHz	$\Delta\alpha$				dB
Standing wave ratio [5150 – 5850] MHz	SWR		1.8	2.0	
Impedance	Z		50		Ω
Power	P			1.0	W
Attenuation	α				
at DC to 2170 MHz		40	45		dB
at 2400 to 2500 MHz		40	43		dB
at 2500 to 3900 MHz		30	39		dB
at 6800 MHz		18	20		dB

Maximum ratings

IEC climatic category (IEC 68-1)		- 40/+ 90/56	
Operating temperature	T_{op}	-40 / +85	°C

Typical passband characteristic


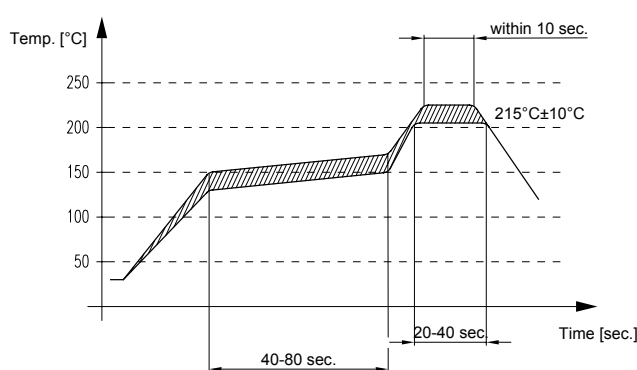
Preliminary Data Sheet
Processing information

ZNr.: 577 (FILT95_2)

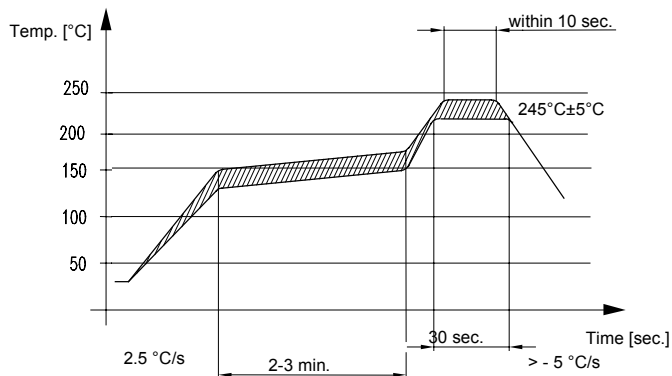
- Wettability acc. to IEC 68-2-58: $\geq 75\%$ (after aging)

Soldering requirements

	Profile for eutectic SnPb solder paste	Profile for leadfree solder paste	
Soldering type	reflow	reflow	
Maximum soldering temperature (measuring point on top surface of the component)	235 (max. 2 sec.) 225 (max. 10 sec.)	260 (max. 2 sec.) 250 (max. 10 sec.)	°C °C

Recommended soldering conditions (infrared):


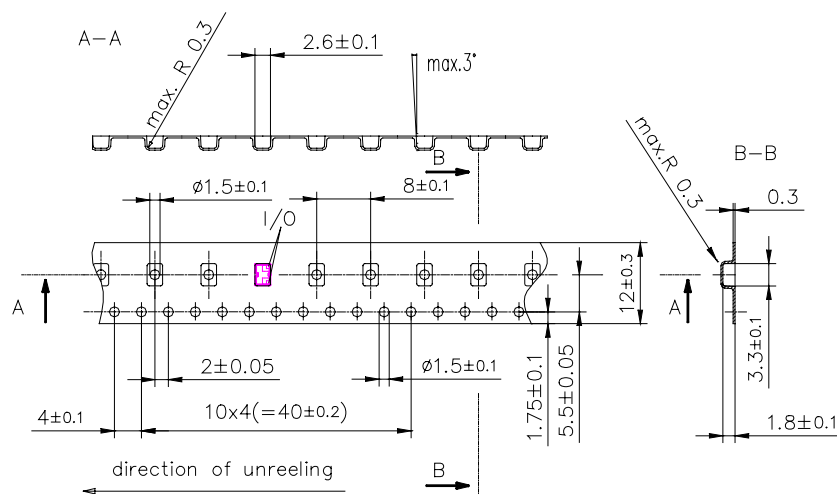
eutectic SnPb solder paste profile



leadfree solder paste profile

Delivery mode

- Blister tape acc. to IEC 286-3, PS, grey
- Pieces/tape: 4000



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The information contained in this data sheet describes the type of component and shall not be considered as guaranteed characteristics. Purchase orders are subject to the General Conditions for the Supply of Products and Services of the Electrical and Electronics Industry recommended by the ZVEI (German Electrical and Electronic Manufacturers' Association), unless otherwise agreed.

ISSUE DATE	19.03.04	ISSUE	P1	PUBLISHER	SAW MWC PD	PAGE	4/4
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